

SAQUA Single Wafer System

System Overview

The Saqua series of 300 mm single-wafer cleaning system utilizes single wafer, precisely controlled spin-spray wet cleaning technology to remove a variety of post metal etch particles and byproducts. The Saqua can be configured with up to eight independent process chambers designed for cleaning feature sizes as small as 14 nm.

Substrate Size: 300 mm

Applicable Material: Silicon

Technology Markets: Digital IC, Power IC, Advanced Packaging

Processes

- Copper Interconnect Cleaning:
 - Post etch clean on via
 - Post etch clean on trench
 - Post etch clean on liner removal
 - Post etch clean on metal hard mask
 - Post etch clean on inter metal etch
 - Backside clean

Production Advantages

- Multitasking parallel processing system; up to eight independently controlled process chambers
- Advanced megasonic cleaning technology
- Liquid chemical ratio real-time control technology
- Particle removal efficiency >99%
- High chemical reclaim efficiency - >99.5%
- Uniform chemical temperature and flow rate control across all process chambers
- Novel wafer backside protection technology
- Independent clean/dirty robots



SAQUA Single Wafer System